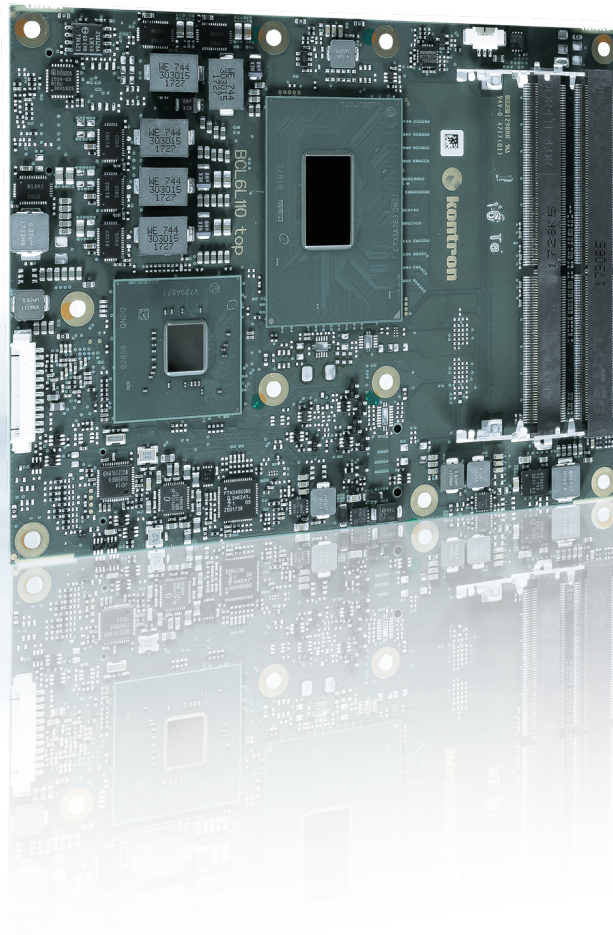


COMe-bCL6(R E2S)



COM Express® Basic Type 6 with 8th/9th Generation Intel® Core™ / Xeon® Processors

- ▶ Intel® 8th/9th Generation Core™ series / Xeon® E family with CM246/QM370 PCH
- ▶ Up to 128 GByte DDR4 non-ECC/ECC memory
- ▶ Optional NVMe SSD onboard
- ▶ Industrial grade versions

POSSIBILITIES START HERE

▶ TECHNICAL INFORMATION

COMPLIANCE	COM Express® basic, Pin-out Type 6
DIMENSIONS (H X W)	125 x 95 mm
CPU	Intel® 8th/9th Generation Core™ series / Xeon® E family For details see table (CPU variants) given below
CHIPSET	Intel® Mobile CM246/Intel® Mobile QM370
MAIN MEMORY	Up to 4x DDR4-2666 SO-DIMM with up to 128 GByte (non-ECC/ECC) (3 rd /4 th socket on request)
GRAPHICS CONTROLLER	Intel® UHD Graphics P630 for Xeon® processor Intel® UHD Graphics 630 for Core™ processors Intel® UHD Graphics 610 for Celeron® processors
ETHERNET CONTROLLER	Intel® I219LM
ETHERNET	10/100/1000 MBit Ethernet
STORAGE	4x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS®	8x PCIe x1, 1x PEG x16
DISPLAY	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	4x USB 3.1 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	Intel® High Definition Audio
OTHER FEATURES	SPI, LPC, SMB, Fast I ² C, Staged Watchdog, RTC, support of Intel® Optane™ memory technology via PCIe
SPECIAL FEATURES	POSCAP capacitors, Trusted Platform Module TPM 2.0, 4k Resolutions, Flexible PEG lane configuration by Setup Option, Rapid shutdown (R E2S variants)
FEATURES ON REQUEST	vPRO (AMT/TXT/AES Support), eDP instead of LVDS, VGA, Intel® Mobile HM370 Chipset, 3 rd /4 th DDR4 SO-DIMM socket, NVMe SSD, Security Chip
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
BIOS	AMI Aptio V
OPERATING SYSTEM	Windows® 10, Linux, VxWorks
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating Extended temperature: -25 °C to +75 °C operating, -30 °C to +85 °C non-operating Industrial temperature: -40 °C to +85 °C operating, -40 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)

▶ CPU VARIANTS

	8th GENERATION								
CPU	E-2176M	i7-8850H	i5-8400H	i3-8100H					
CORES	6	6	4	4					
FREQUENCY BASE/TURBO	2.7/4.4 GHz	2.6/4.3 GHz	2.5/4.2 GHz	3.0/- GHz					
TDP	45 W/35 W	45 W/35 W	45 W/35 W	45 W/35 W					
CACHE	12 MByte	9 MByte	8 MByte	6 MByte					
	9th GENERATION								
CPU	E-2276ME	E-2276ML	E-2254ME	E-2254ML	i7-9850HE	i7-9850HL	i3-9100HL	G4930E	G4932E
CORES	6	6	4	4	6	6	4	2	2
FREQUENCY BASE/TURBO	2.8/4.5 GHz	2.0/4.2 GHz	2.6/3.8 GHz	1.7/3.5 GHz	2.7/4.4 GHz	1.9/4.1 GHz	1.6/2.9 GHz	2.4/- GHz	1.9/- GHz
TDP	45 W/35 W	25 W	45 W/35 W	25 W	45 W/35 W	25 W	25 W	35 W	25 W
CACHE	12 MByte	12 MByte	8 MByte	8 MByte	9 MByte	9 MByte	6 MByte	2 MByte	2 MByte

